

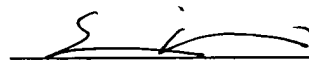
REMARKS

Further to the amendment filed July 14, 2003, claims 41, 42, 54 and 55 have been further amended to better recite the features of the present invention. Claims 45-47 and 58 have also been amended to correct minor grammatical errors. The Applicants note that the specification discloses that the conductive particle includes a 7.5 μm resilient particle covered with a 1000Å Au film. Since 1000Å equals 0.1 μm , the final diameter of the conductive particle is 7.7 μm . Therefore, as a result of the application of pressure as described on pages 11-12 of the previously filed amendment, the particles decrease in size by at least 35%.

That is, according to the specification, a pressure of 2.4 kg/cm^2 is applied when a resin hardens. This pressure may result in a gap between two electrodes narrower than 5 μm , which is a diameter of a hard particle. First, by pressing the hard particle to an electrode, a dent may be created on a surface of the electrode. Then, the gap between electrodes would be narrower than 5 μm due to the dent. Second, it is possible that the electrodes press the hard particle somewhat with a pressure applied by the electrodes. As a result, a diameter of a resilient particle is less than 5 μm and compression over 35% occurs. As such, the Applicants respectfully submit that the recitation that the diameter of the particle decreases by at least 35% is supported by the specification of the present invention.

Should the Examiner believe that anything further would be desirable to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned attorney at the telephone number listed below.

Respectfully submitted,



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